

In the Abstract

Please amend the Abstract as follows:

J (~~An interposer with cache memory devices, a passive element, and conductive pads~~
has A method of assembling a multi-chip device may include coupling solder balls attached
only to selected ones of the conductive pads on an interposer with cache memory devices.

The cache memory devices are then tested, and the interposer is coupled to a substrate with
the solder balls for further assembly only if the test is passed.